



Material Content Data Sheet



Sales Product Name	TLF35584QVVS2			Issued	9. January 2019			
MA#	MA004419002							
Package	PG-VQFN-48-31			Weight*	129.86 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.311	3.32	3.32	33195	33195
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		552	
	non noble metal	iron	7439-89-6	1.433	1.10		11036	
wire	non noble metal	copper	7440-50-8	58.193	44.81	45.98	448106	459832
	non noble metal	copper	7440-50-8	0.634	0.49	0.49	4883	4883
	encapsulation	organic material	carbon black	1333-86-4	0.183	0.14		1406
encapsulation	plastics	epoxy resin	-	7.730	5.95		59522	
	inorganic material	silicondioxide	60676-86-0	52.952	40.78	46.87	407752	468680
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	19993	19993
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4727	4727
glue	plastics	epoxy resin	-	0.260	0.20		1999	
	noble metal	silver	7440-22-4	0.869	0.67	0.67	6691	8690
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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